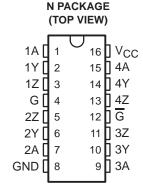
SLLS121D - AUGUST 1990 - REVISED APRIL 1998

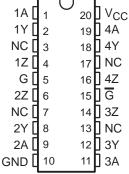
- Meets or Exceeds ANSI Standards EIA/TIA-422-B and RS-485 and ITU Recommendation V.11
- **High-Speed Advanced Low-Power Schottky** Circuitry
- **Designed for 20-MBaud Operation in Both** Serial and Parallel Applications
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- **Low Supply-Current Requirements:** 55 mA Max
- Wide Positive and Negative Input/Output **Bus-Voltage Ranges**
- Driver Output Capacity . . . ±60 mA
- **Thermal Shutdown Protection**
- **Driver Positive and Negative Current** Limiting
- **Logically Interchangeable With SN75172**

description

The SN75ALS172A comprises four line drivers with 3-state differential outputs. They are designed to meet the requirements of ANSI Standards EIA/TIA-422-B and RS-485 and ITU Recommendation V.11. This device is optimized for balanced multipoint bus transmission at rates of up to 20 Mbaud. Each driver features wide positive and negative common-mode output voltage ranges, making it suitable for party-line applications in noisy environments.







NC - No internal connection

The SN75ALS172A provides positive- and negative-current limiting and thermal shutdown for protection from line-fault conditions on the transmission bus line. Shutdown occurs at a junction temperature of approximately 150°C.

The SN75ALS172A is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

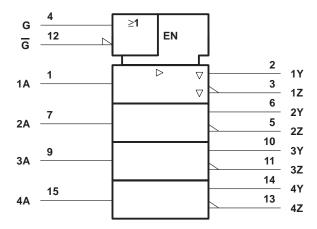


FUNCTION TABLE (each driver)

| INPUT | ENA | BLES | OUTPUTS | | |
|-------|-----|------|---------|---|--|
| Α | G | G | Υ | Z | |
| Н | Н | Х | Н | L | |
| L | Н | X | L | Н | |
| Н | Х | L | Н | L | |
| L | Х | L | L | Н | |
| Х | L | Н | Z | Z | |

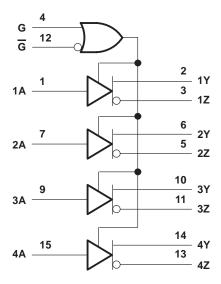
H = high level, L = low level, X = irrelevant, Z = high impedance (off)

logic symbol†



 $[\]mbox{†}$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the N package.

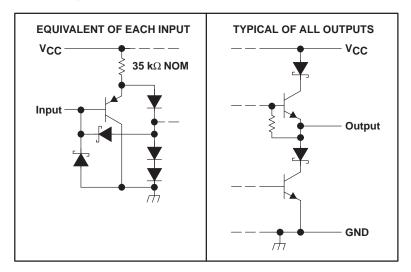
logic diagram (positive logic)



Pin numbers shown are for the N package.



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage, V _{CC} (see Note 1) | 7 V |
|--|----------------|
| Input voltage, V _I | 7 V |
| Output voltage range, V _O | –9 V to 14 V |
| Continuous total dissipation | |
| Storage temperature range, T _{stg} | –65°C to 150°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

| PACKAGE | $T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING | DERATING FACTOR | T _A = 70°C POWER RATING | T _A = 85°C POWER RATING |
|---------|--|--------------------|---------------------------------------|---------------------------------------|
| DW | 1125 mW | 9 mW/°C | 720 mW | 585 mW |
| N | 1150 mW | 9.2 mW/°C | 736 mW | 598 mW |

recommended operating conditions

| | MIN | NOM | MAX | UNIT |
|--|------|-----|----------|------|
| Supply voltage, V _{CC} | 4.75 | 5 | 5.25 | V |
| High-level input voltage, VIH | 2 | | | V |
| Low-level input voltage, V _{IL} | | | 0.8 | V |
| Common-mode output voltage, V _{OC} | | | 12 -7 | V |
| High-level output current, IOH | | | -60 | mA |
| Low-level output current, IOL | | | 60 | mA |
| Operating free-air temperature, T _A | 0 | | 70 | °C |



SLLS121D - AUGUST 1990 - REVISED APRIL 1998

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| | PARAMETER | TEST | CONDITIONS | MIN | TYP [†] | MAX | UNIT |
|-------------------|---|---|---------------------------------------|------------------------|------------------|---------|------|
| VIK | Input clamp voltage | I _I = -18 mA | | | | -1.5 | V |
| VO | Output voltage | IO = 0 | | 0 | | 6 | V |
| V _{OD1} | Differential output voltage | I _O = 0 | | 1.5 | | 6 | V |
| IVonal | Differential output voltage | $V_{CC} = 5 V$, | R_L = 100 Ω, See Figure 1 | 1/2 V _{OD1} o | r 2‡ | | V |
| IVOD2I | Differential output voltage | $R_L = 54 \Omega$, | See Figure 1 | 1.5 | 2.5 | 5 | V |
| VOD3 | Differential output voltage | See Note 2 | | 1.5 | | 5 | V |
| Δ V _{OD} | Change in magnitude of differential output voltage§ | R_L = 54 Ω or 100 Ω , | See Figure 1 | | | ±0.2 | V |
| Voc | Common-mode output voltage¶ | R_L = 54 Ω or 100 Ω , | See Figure 1 | | | 3 –1 | V |
| Δ VOC | Change in magnitude of common-mode output voltage§ | $R_L = 54 \Omega \text{ or } 100 \Omega,$ | See Figure 1 | | | ±0.2 | ٧ |
| IO | Output current with power off | $V_{CC} = 0$, | $V_O = -7 \text{ V to } 12 \text{ V}$ | | | ±100 | μΑ |
| loz | High-impedance-state output current | $V_0 = -7 \text{ V to } 12 \text{ V}$ | | | | ±100 | μА |
| lН | High-level input current | V _I = 2.7 V | | | | 20 | μΑ |
| I _{IL} | Low-level input current | V _I = 0.4 V | | | | -100 | μΑ |
| los | Short-circuit output current | $V_0 = -7 \text{ V to } 12 \text{ V}$ | | | | ±250 | mA |
| laa | Supply current (all drivers) | No load | Outputs enabled | | 36 | 55 | mA |
| Icc | Supply current (all drivers) | INO IOAU | Outputs disabled | | 15 | 30 | IIIA |

 $^{^{\}dagger}$ All typical values are at V_{CC} = 5 V and T_A = 25°C.

NOTE 2: See EIA Standard RS-485, Figure 3-5, Test Termination Measurement 2.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_1 = 50 \text{ pF}$

| | PARAMETER | TEST CO | MIN | TYP [†] | MAX | UNIT | |
|--------------------|-------------------------------------|----------------------|--------------|------------------|-----|------|----|
| ^t d(OD) | Differential-output delay time | $R_L = 54 \Omega$, | See Figure 2 | 9 | 15 | 22 | ns |
| ^t PZH | Output enable time to high level | $R_L = 110 \Omega$, | See Figure 3 | 30 | 45 | 70 | ns |
| tPZL | Output enable time to low level | $R_L = 110 \Omega$, | See Figure 4 | 25 | 40 | 65 | ns |
| ^t PHZ | Output disable time from high level | $R_L = 110 \Omega$, | See Figure 3 | 10 | 20 | 35 | ns |
| ^t PLZ | Output disable time from low level | $R_L = 110 \Omega$, | See Figure 4 | 10 | 30 | 45 | ns |

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.



[‡] The minimum V_{OD2} with a 100-Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

[§] $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

In ANSI Standard EIA/TIA-422-B, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS}.

PARAMETER MEASUREMENT INFORMATION

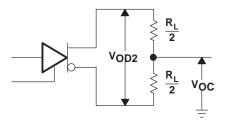
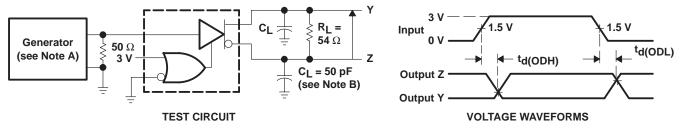


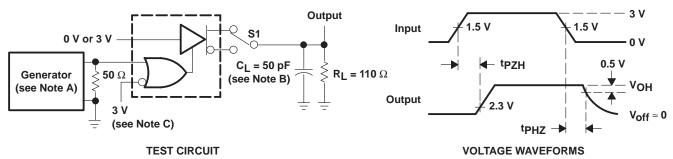
Figure 1. Differential and Common-Mode Output Voltages



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, $Z_O = 50 \Omega$, duty cycle = 50%, $t_f \le 5$ ns, $t_r \le 5$ ns.

B. C_L includes probe and stray capacitance.

Figure 2. Differential Output Test Circuit and Voltage Waveforms



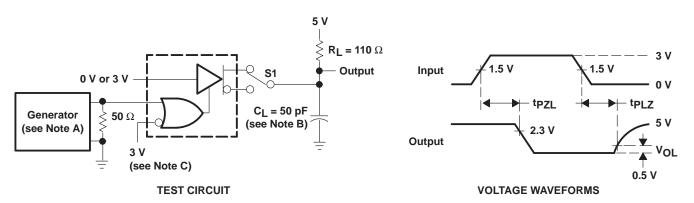
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, $Z_O = 50 \Omega$, duty cycle = 50%, $t_f \le 5$ ns,

B. C_L includes probe and stray capacitance.

C. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 3. Test Circuit and Voltage Waveforms, tpzH and tpHZ

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, $Z_O = 50 \Omega$, duty cycle = 50%, $t_f \le 5$ ns, $t_f \le 5$ ns.
 - B. \dot{C}_L includes probe and stray <u>capacitance</u>.
 - C. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 4. Test Circuit and Voltage Waveforms, tpzI and tpI 7





PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | _ | Pins | Package | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|--------|--------------|---------|------|---------|----------------------------|------------------|--------------------|--------------|----------------|---------|
| | (1) | | Drawing | | Qty | (2) | (6) | (3) | | (4/5) | |
| SN75ALS172ADW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 75ALS172A | Samples |
| SN75ALS172ADWR | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 75ALS172A | Samples |
| SN75ALS172AN | ACTIVE | PDIP | N | 16 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | N / A for Pkg Type | 0 to 70 | SN75ALS172AN | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

6-Feb-2020

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN75ALS172ADWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |

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*All dimensions are nominal

| Device | Package Type | Package Drawing Pins | | SPQ | Length (mm) | Width (mm) | Height (mm) | |
|----------------|--------------|----------------------|----|------|-------------|------------|-------------|--|
| SN75ALS172ADWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 | |

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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